



RECOMMENDED PCB LAYOUT, PCB THICKNESS: 1.57MM
 UNSPECIFIED TOLERANCE ±0.05MM

1. MATERIAL:
 HOUSING: HIGH TEMP. THERMOPLASTIC, LCP UL94V-0,
 COLOUR: BLACK, GLOW WIRE COMPATIBLE
 CONTACT: COPPER ALLOY.
2. PLATING FINISH
 CONTACT AREA : OPTIONAL PLATING, SEE PART NUMBER LOGIC
 SOLDER AREA : 100µ" MINIMUM MATTE TIN
 UNDER PLATING: 50µ" MINIMUM NICKEL UNDERPLATED.
3. MATE WITH AICC RECEPTACLE: 10161719, 10168565 & 10171526
4. PRODUCT SPECIFICATION : GS-12-1706
5. PACKING SPECIFICATION : GS-14-2802
6. APPLICATION SPECIFICATION: GS-20-0704
7. IN ACCORDANCE WITH PCIE SPECIFICATION REV 5.1, VER 1
8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW OVEN.
9. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER.
10. LEAD FREE PRODCUTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
11. PART NUMBER LOGIC

10163894-XX X X X X X L F

NO. OF POWER PINS LOADED _____
 12 → 12 PINS

NO. OF SIGNAL PINS LOADED _____
 4 → 4 PINS

TERMINATION: _____
 0 : 3.18MM
 1 : 2.20MM

PLATING OPTION: _____
 1: 100µ" MATTE TIN OVERALL
 2: GOLD FLASH OVERALL
 3: 15µ" GOLD ON CONTACT AREA AND MATTE TIN ON TERMINAL AREA
 4: 30µ" GOLD ON CONTACT AREA AND MATTE TIN ON TERMINAL AREA

PACKING OPTION: _____
 0 : TRAY
 1 : TAPE AND REEL (24 MM PITCH)
 2 : TAPE AND REEL (20 MM PITCH)

LOADING OPTION: _____
 0: STANDARD

spec ref		dr	Nithin N-C	2023/02/08	projection 	MM ←→	size	A3	scale	4:1
tolerance std		eng	Premchand, Pra	2025/04/02			ecn no	ELX-I-55235-1		
ISO 406 ISO 1101		chr	-	-			rel level	Released		
TOLERANCES UNLESS OTHERWISE SPECIFIED		appr	Kuriakose, San	2025/04/02			product family	MINITEK POWER		
surface	linear	0.X	±0.25	Amphenol FCI	HYBRID R/A HEADER WITH ROUND PEG	dwg no	10163894	rev	C	
		0.XX	±0.20							
		0.XXX	±							
ISO 1302	angular	0°	±2°	amphenol-icc.com	cat. no.	-	Product - Customer Drw	sheet 2 of 2		